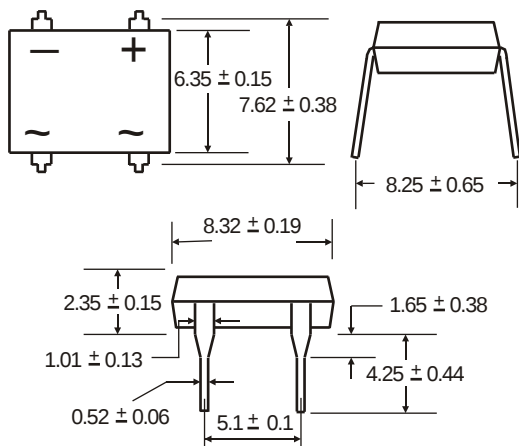


DB



Dimensions in millimeters (1mm =0.0394")

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C/10 seconds / 0.375"(9.5mm) led length at 5 lbs., (2.3kg)tension

MECHANICAL DATA

Case: Molded plastic body

Lead: Solder plated

Polarity: Polarity symbols marked on case

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, For capacitive load derate current by 20%.

	SYMBOLS	DB 151	DB 152	DB 153	DB 154	DB 155	DB 156	DB 157	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at $T_A=40^\circ\text{C}$	$I_{F(AV)}$	1.5							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60							Amps
Maximum instantaneous forward voltage drop per bridge element at 1.5A	V_F	1.1							Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	10 500							μA μA
Typical thermal resistance (NOTE)	$R_{\theta JA}$ $R_{\theta JL}$	40 15							
Operating temperature range	T_J	-55 to +150							$^\circ\text{C}$
storage temperature range	T_{STG}	-55 to +150							$^\circ\text{C}$

NOTE: Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. mounted with 0.47x0.47"(12x12mm) copper pads.

RATINGS AND CHARACTERISTIC CURVES DB151 THRU DB157

